

The RoHS Directive

Since the publication of 2002/95/EC of January 27th, 2003 and the amendment of August 2005 and June 2011, Fagor Electronica S.Coop. is committed, with the collaboration of its subcontractors and suppliers, to eliminating or at least to reducing to tolerated values by weight in homogeneous materials the six banned substances:

Lead (0.1 %)
Mercury (0.1 %)
Cadmium (0.01 %)
Hexavalent chromium (0.1 %)
Polybrominated biphenyls (PBB) (0.1 %)
Polybrominated diphenyl ethers (PBDE) (0.1 %)

These six substances are not present in the products manufactured and sold by Fagor Electronica S. Coop, exception made of Lead (Pb) which is either:

An element of the internal die solder to leads or to the lead-frame which is waived by the exception # 8(e):

Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead (ELV Directive 2000/53/EC, as well)

An element of the glass used for die passivation which is waived by the exception #10:

Electrical components which contain lead in a glass or ceramic matrix compound except glass in bulbs and glaze of spark plugs

Or, an element of plating of the contacts in concentrations < 0.1%

Note:

The new EU-DIRECTIVE 2011-65-EU (RoHS 2) which comes into force on January 2nd, 2013 includes mentioned exceptions

ANNEX III

Applications exempted from the restriction in Article 4(1):

7(a)

Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

7(c)-I

Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound

Quality & Environment

Fagor Electrónica Semiconductores

The new EU-DIRECTIVE 2015/863 of 31 March 2015 amending Annex II to Directive 2011/65/EU of the European Parliament includes these restricted substances

Ftalato de bis(2-etilexilo) (DEHP) (0,1 %)

Ftalato de bencilo y butilo (BBP) (0,1 %)

Ftalato de dibutilo (DBP) (0,1 %)

Ftalato de diisobutilo (DIBP) (0,1 %)

These four substances are not present in the products manufactured Fagor Electronica S. Coop

Material Composition Declaration (MCD)

Information in weight and weight percentages of the elements in all homogeneous materials, as well as on the concentrations of the RoHS banned substances of all homogeneous materials of each device sold by Fagor Electronica is provided upon request.

The information has been organized according to packages. Items assembled in the same package have basically the same structure and materials composition; although in some cases, due to different chip size or leads or lead-frames with minor differences within the same package, quantities of some particular material could be slightly different.

The information contained in these declarations has been prepared in the most accurate possible way. As consequence of minor changes, which do not require prior notification to customers, the weight percentage of some element could change slightly.

Analysis reports on the concentration of the banned substances of each homogeneous material, performed by a qualified laboratory, are available upon request.